



Material Composition Sheet

Product: GS9023BCVE3
Package Type: 12x12mm 100pin TQFP Lead free
Manufacturer: Gennum Corporation

Date: 11-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		23.82	Polyimide	0.42	1.76	17632
			Si	23.40	98.23	982368
			Sub-total:	23.82	99.99	1000000
Die Attach		11.80	Ag	10.00	84.74	847458
			Epoxy Resin	1.80	15.25	152542
			Sub-total:	11.80	99.99	1000000
Lead Finish External	Sn/Bi 98/2	17.35	Bi	0.35	2.01	20173
			Sn	17.00	97.98	979827
			Sub-total:	17.35	99.99	1000000
Lead Finish Internal		0.14	Ag	0.14	100.00	1000000
Lead Frame		140.00	Ag	0.14	0.10	1000
			Cu	136.00	97.14	971429
			Fe	3.58	2.55	25571
			Zn	0.28	0.20	2000
			Sub-total:	140.00	99.99	1000000
Mold Compound		244.30	Carbon Black	3.60	1.47	14736
			Epoxy Resin	17.00	6.95	69587
			Organophosphorus compound	1.20	0.49	4912
			Phenol Resin	9.50	3.88	38887
			SiO2	213.00	87.18	871879
			Sub-total:	244.30	99.97	1000001
Wires		1.30	Au	1.30	100.00	1000000
			Sub-total:	1.30	100.00	1000000
Total:		438.71				

GENNUM CORPORATION

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